



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20180531000A

Datasheet for OPA354-OPA4354, OPA357-OPA2357, OPA355-OPA3355

Information Only

Error Correction (Datasheet Update #3): TSSOP package type device inclusion in the page 2 of the customer specific letter.

Date: June 11, 2018

To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is information-only announcement of a change to product data sheets for devices that are currently offered by Texas Instruments. The details of the change are described on the following pages.

The changes within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
OPA3355EA/2K5	null

Technical details of this Datasheet Change follow on the next page(s).

PCN Number:	20180531000A	PCN Date:	June 11, 2018
Title:	Datasheet for OPA354-OPA4354, OPA357-OPA2357, OPA355-OPA3355		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials	
		<input type="checkbox"/> Wafer Fab Process	

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing datasheet updates in an information only notification. The product datasheets are being updated as summarized in the revision history provided below.

Error Correction (Datasheet Update #3): TSSOP package type device inclusion in the page 2 of the customer specific letter.

Datasheet Update# 1

Literature Number Update- From: SBOS233F To: SBOS233G



OPA354, OPA2354, OPA4354

SBOS233G – MARCH 2002 – REVISED APRIL 2018

Changes from Revision F (June 2016) to Revision G

Page

- Deleted table note about input pins and input signals from *Absolute Maximum Ratings* table 6

Link to Full Datasheet: <http://www.ti.com/product/OPA354>

Affected Products:

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (5)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)
OPA2354AIDDA	ACTIVE	SO PowerPAD	DDA	8	75	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	OPA 2354A
OPA2354AIDDA G3	ACTIVE	SO PowerPAD	DDA	8	75	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	OPA 2354A
OPA2354AIDDA R	ACTIVE	SO PowerPAD	DDA	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	OPA 2354A
OPA2354AIDDA R G3	ACTIVE	SO PowerPAD	DDA	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	OPA 2354A
OPA2354AIDGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	OACI
OPA2354AIDGKR G4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	OACI
OPA2354AIDGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	OACI
OPA2354AIDGKT G4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	OACI
OPA354AIDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OABI
OPA354AIDBVR G4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OABI
OPA354AIDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OABI
OPA354AIDBVT G4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OABI
OPA354AIDDA	ACTIVE	SO PowerPAD	DDA	8	75	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	OPA 354A
OPA354AIDDA G3	ACTIVE	SO PowerPAD	DDA	8	75	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	OPA 354A
OPA354AIDDA R	ACTIVE	SO PowerPAD	DDA	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	OPA 354A
OPA4354AID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA4354A
OPA4354AIDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA4354A

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)
OPA4354AIDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA4354A
OPA4354AIDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA4354A
OPA4354AIPWR	ACTIVE	TSSOP	PW	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 4354A
OPA4354AIPWRG4	ACTIVE	TSSOP	PW	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 4354A
OPA4354AIPWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 4354A
OPA4354AIPWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 4354A

Datasheet Update# 2

Literature Number Update- From: SBOS235E To: SBOS235F



OPA357, OPA2357

SBOS235F –MARCH 2002–REVISED APRIL 2018

Changes from Revision E (May 2009) to Revision F

Page

• Added Device Information table, Pin Functions table, ESD Ratings table, Recommended Operating Conditions table, Thermal Information table, Overview section, Functional Block Diagram section, Feature Description section, Device Functional Modes section, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section	1
• Changed MSOP to VSSOP throughout document	1
• Deleted DDA package (SO-8 PowerPAD) from document	1
• Changed MSOP to VSSOP throughout document	1
• Added WEBENCH Features bullet	1
• Deleted OADI from DBV pin drawing	3
• Deleted Package/Ordering Information table	4
• Deleted footnote from Signal input pins parameter in Absolute Maximum Ratings table	4
• Changed Temperature Range section of Electrical Characteristics table: changed θ_{JA} to $R_{\theta JA}$ and deleted Specified range, Operating range, and Storage range parameters	6
• Added OPAX357 Comparison section and moved OPAX357 Related Products table to this section from page 1	14
• Deleted first paragraph of Power Dissipation section	26
• Changed PCB Layout title to Layout Guidelines	26
• Deleted PowerPAD Thermal Enhanced Package and PowerPAD Assembly Process sections	26
• Added Custom Design With WEBENCH® Tools section	27

Link to Full Datasheet: <http://www.ti.com/product/OPA2357>

Affected Products:

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)
OPA2357AIDGSR	ACTIVE	VSSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	BBG
OPA2357AIDGSRG4	ACTIVE	VSSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	BBG
OPA2357AIDGST	ACTIVE	VSSOP	DGS	10	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	BBG
OPA2357AIDGSTG4	ACTIVE	VSSOP	DGS	10	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	BBG
OPA357AIDBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OADI
OPA357AIDBVRG4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OADI
OPA357AIDBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OADI
OPA357AIDBVTG4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OADI

Datasheet Update# 3

Literature Number Update- From: SBOS195D To: SBOS195E



OPA355, OPA2355, OPA3355
SBOS195E – MARCH 2001 – REVISED APRIL 2018

Changes from Revision D (January 2004) to Revision E	Page
• Updated data sheet to latest TIS documentation and translation standards	1
• Changed pin type typo from MSOP to VSSOP in <i>Description</i> section	1
• Added <i>Device Information</i> table	1
• Changed pin 1 of OPA355 D (SOIC) pinout drawing from "OUT" to "NC"	4
• Deleted the <i>Absolute Maximum Ratings</i> tablenote: Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current limited to 10mA or less.....	7
• Added <i>ESD Ratings</i> table	7
• Added <i>Recommended Operating Conditions</i> table	7
• Added <i>Thermal Information</i> tables	8
• Changed pin type typo from MSOP to VSSOP in <i>Electrical Characteristics</i> section	10
• Deleted the test conditions statement from <i>Typical Characteristics</i> graphs and moved the conditions to tablenotes below the graphs	11
• Added <i>Detailed Description</i> section	16
• Added <i>Functional Block Diagram</i> graphic	16
• Deleted <i>Input and ESD Protection</i> section	16
• Added <i>Application and Implementation</i> section	18
• Deleted <i>Internal ESD Protection</i> application	18
• Added <i>Power Supply Recommendations</i> section	25
• Added <i>Layout Guidelines</i> section	25

Link to Full Datasheet: <http://www.ti.com/product/OPA355>

Affected Products:

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)
OPA2355DGSA/250	ACTIVE	VSSOP	DGS	10	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	D55
OPA2355DGSA/250G4	ACTIVE	VSSOP	DGS	10	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	D55
OPA3355EA/250	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 3355EA
OPA3355EA/250G4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 3355EA
OPA3355EA/2K5	ACTIVE	TSSOP	PW	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 3355EA
OPA3355UA	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA3355UA
OPA3355UAG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA3355UA
OPA355NA/250	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	C55
OPA355NA/250G4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	C55
OPA355NA/3K	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	C55
OPA355NA/3KG4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	C55
OPA355UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 355UA
OPA355UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 355UA
OPA355UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 355UA
OPA355UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 355UA

Reason for Change:
To accurately reflect device characteristics.
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.
Changes to product identification resulting from this PCN:
None.

For TI datasheet updates, please consider mapping the TI device to a customer "Alert". Alerts can be managed from the ti.com website at <https://www.ti.com/myti/docs/maintainalert.tsp>

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com